



Discription

Low capacitance bidirectional ElectroStatic Discharge (ESD) protection diode in a DFN1006(SOD-882) leadless ultra small Surface-Mounted Device (SMD) plastic package designed to protect one signal line from the damage caused by ESD and other transients.

Features

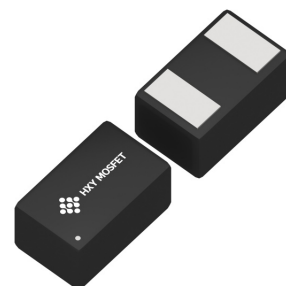
- ★ BidirectionalESDprotectionofoneline
- ★ Low operating voltage:24V
- ★ Low clamping voltage $V_C = 50V @ 3A$
- ★ Responsetimeistypically<1ns
- ★ UltraLowLeakage:nAlevel
- ★ IEC 61000-4-2: level 4 (ESD)
- ★ IEC 61000-4-5 (surge): IPPMQ100 A

Applications

- ★ Portable electronics
- ★ Computersandperipherals
- ★ Audio and video equipment
- ★ Cellular handsets and accessories
- ★ Communication systems
- ★ Power supplies

Ordering information

Product ID	Pack	Qty(PCS)
D24V0L1B2LPS-7B	DFN1006-2L	10000



DFN1006-2L



Circuit Diagram



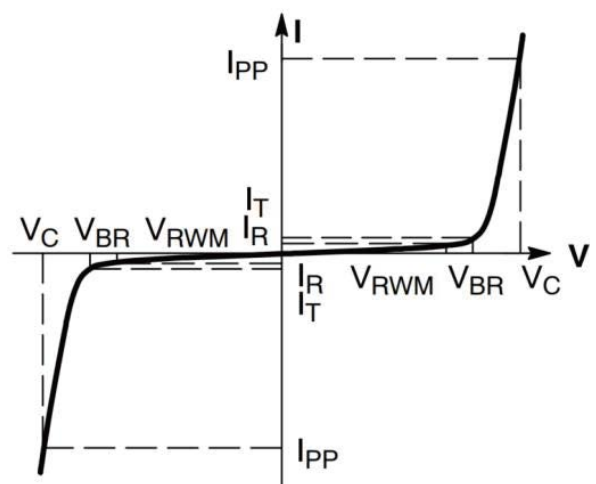
Absolute Ratings($T_{amb} = 25^{\circ}\text{C}$)

Parameter	Symbol	Value	Unit
Peak Pulse Power ($t_p = 8/20\mu\text{s}$)	P_{PPM}	150	W
Maximum lead temperature for soldering during 10s	T_L	260	$^{\circ}\text{C}$
Storage Temperature Range	T_{stg}	-55 to +150	$^{\circ}\text{C}$
Operating Temperature Range	T_{OP}	-55 to +150	$^{\circ}\text{C}$
Maximum junction temperature	T_j	150	$^{\circ}\text{C}$
ESD voltage IEC 61000-4-2 (air discharge)	V_{ESD}	15	kV
ESD voltage IEC 61000-4-2 (contact discharge)	V_{ESD}	8	kV

Electrical Characteristics

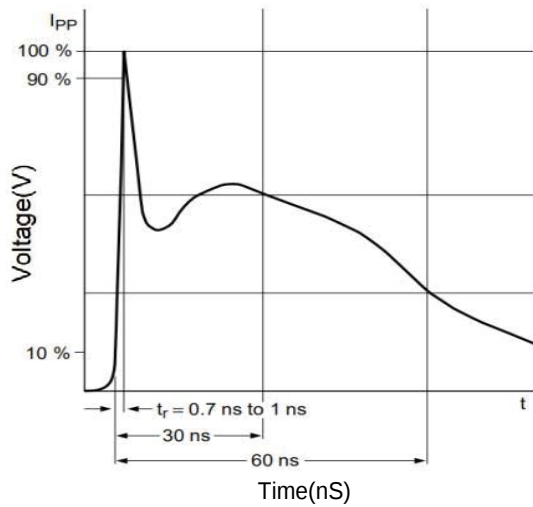
Parameter	Symbol	Min	Typ	Max	Unit	Condition
Reverse Working Voltage	V_{RWM}	--	--	24	V	
Breakdown Voltage	V_{BR}	26	--	32	V	$I_T=1\text{mA}$
Leakage Current I_{Leak}	I_R	--	--	1.0	μA	$V_{RWM}=5.0\text{V}$
Clamping Voltage	V_C	--	--	40	V	$I_{PP}=1\text{A}, t_p=8/20\mu\text{s}$
Clamping Voltage	V_C	--	--	50	V	$I_{PP}=3\text{A}, t_p=8/20\mu\text{s}$
Junction Capacitance	C_J	--	8	15	pF	$V_R=0\text{V}, f=1\text{MHz}$

Symbol	Parameter
I_{PPM}	Maximum Reverse Peak Pulse Current
V_C	Clamping Voltage @ I_{PP}
V_{RWM}	Working Peak Reverse Voltage
I_R	Reverse Leakage Current @ V_{RWM}
I_T	Test Current
V_{BR}	Breakdown Voltage @ I_T

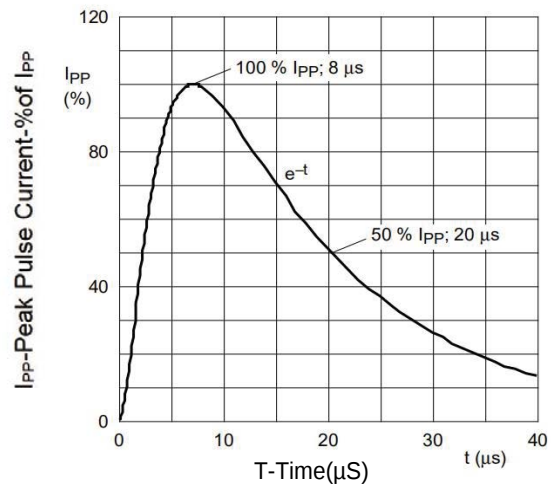




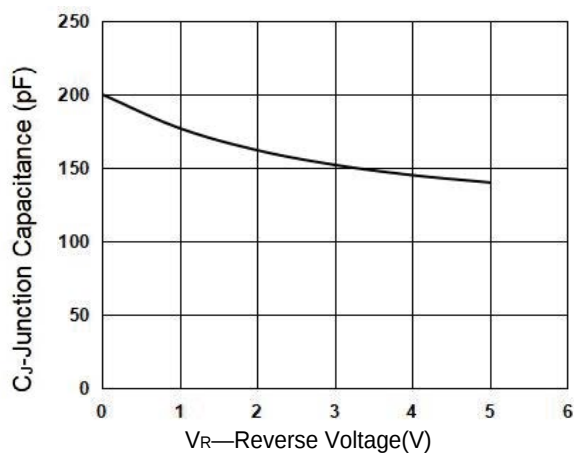
Typical Characteristics



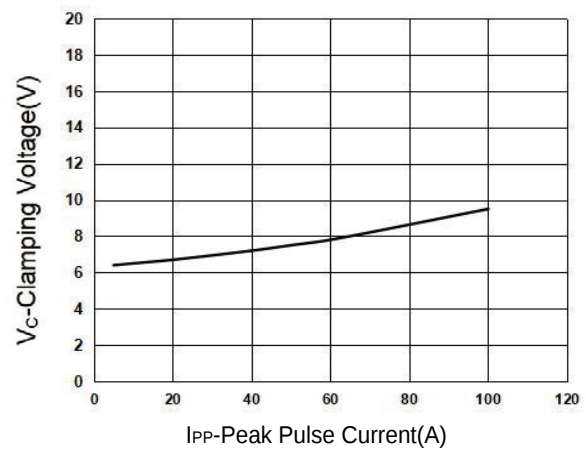
IEC61000-4-2 Pulse Waveform



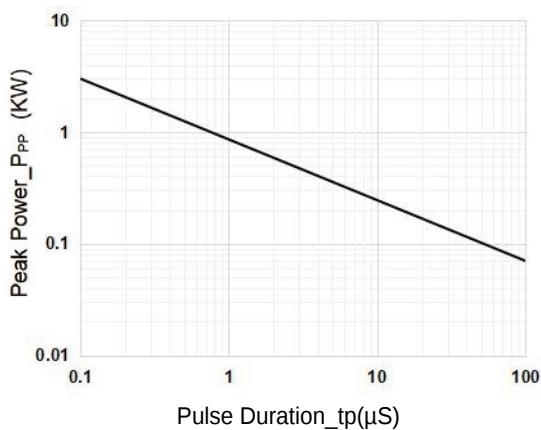
IEC61000-4-5 8X20μs Pulse Waveform



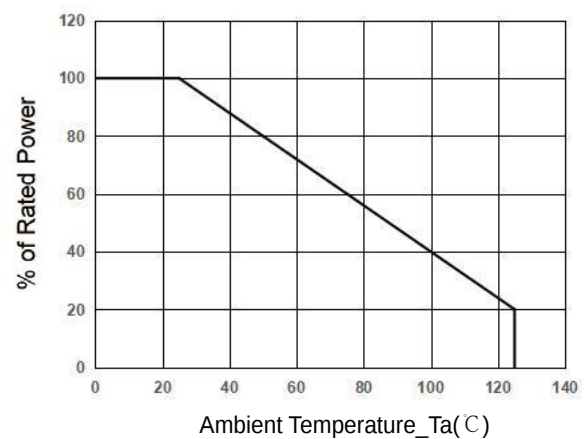
Junction Capacitance vs. Reverse Voltage



Clamping Voltage vs. Peak Pulse Current



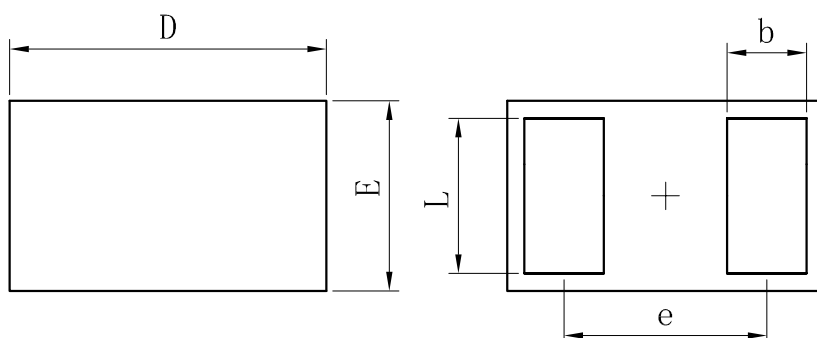
Peak Pulse Power vs. Pulse Time



Power Derating Curve

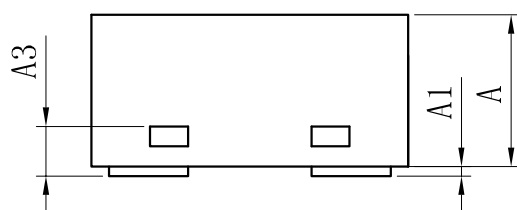


Outline And Dimensions



TOP VIEW

BOTTOM VIEW



SIDE VIEW

DFN1006-2L			
Dim	Min	Typ	Max
D	0.95	1.00	1.05
E	0.55	0.60	0.65
e	–	0.64	–
L	0.44	0.49	0.54
b	0.20	0.25	0.30
A	0.43	0.48	0.53
A1	0	–	0.05
A3	0.127REF.		
All Dimensions in mm			

Soldering Footprint



Dimensions	(mm)
c	0.70
G	0.30
X	0.40
X1	1.10
Y	0.70



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